

TOSHIBA LED LAMP InGaAlP ORANGE LIGHT EMISSION

# TLOH262

PANEL CIRCUIT INDICATOR

- 3.1 mm DIAMETER (T1)
- InGaAlP ORANGE LED
- All Plastic Mold Type.
- Colorless Clear Lens
- Low Drive Current, High Intensity Orange Light Emission  
Recommended Forward Current :  $I_F = 1\sim 20$  mA (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity
- APPLICATIONS : Suitable for Backlighting.

MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

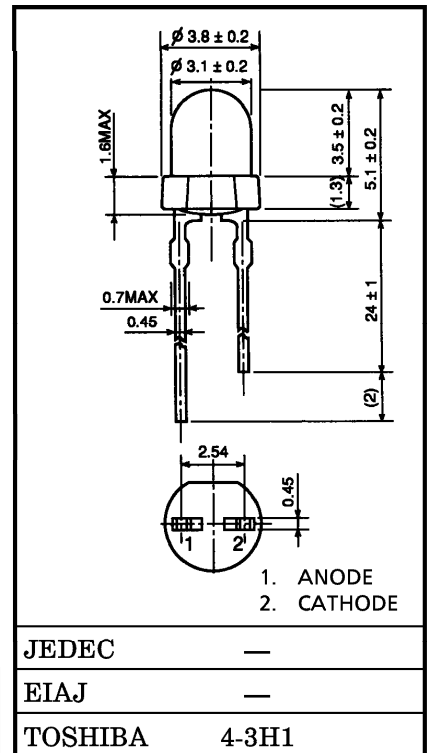
CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_F$	50	mA
Reverse Voltage	$V_R$	4	V
Power Dissipation	$P_D$	125	mW
Operating Temperature Range	$T_{opr}$	-30~85	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-40~120	$^\circ\text{C}$

ELECTRICAL AND OPTICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Forward Voltage		$V_F$	$I_F = 20$ mA	—	2.1	2.5	V
Reverse Current		$I_R$	$V_R = 4$ V	—	—	50	$\mu\text{A}$
Luminous Intensity	TLOH262	$I_V$	$I_F = 20$ mA (Note)	153	450	—	mcd
	TLOH262 (PQ)			153	—	736	
Peak Emission Wavelength		$\lambda_p$	$I_F = 20$ mA	—	612	—	nm
Spectral Line Half Width		$\Delta\lambda$	$I_F = 20$ mA	—	15	—	nm
Dominant Wavelength		$\lambda_d$	$I_F = 20$ mA	—	605	—	nm

(Note) : Lamps are classified into the following ranks according to their luminous intensity.  
 Measurement tolerance for each limit is  $\pm 15\%$ .  
 P : 180-360 mcd, Q : 320-640 mcd, R : 560-1120 mcd.

Unit in mm



Weight : 0.14 g

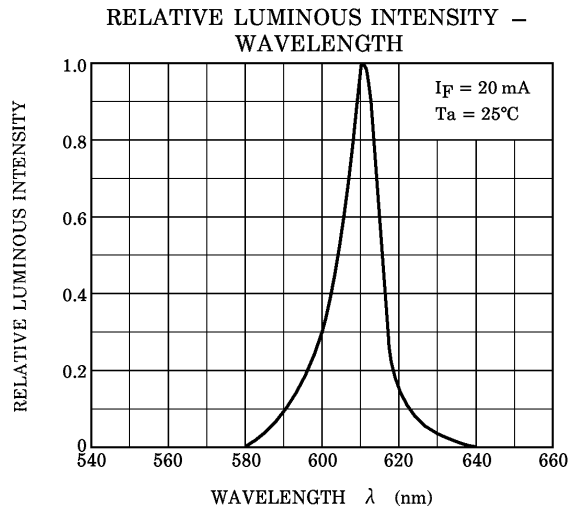
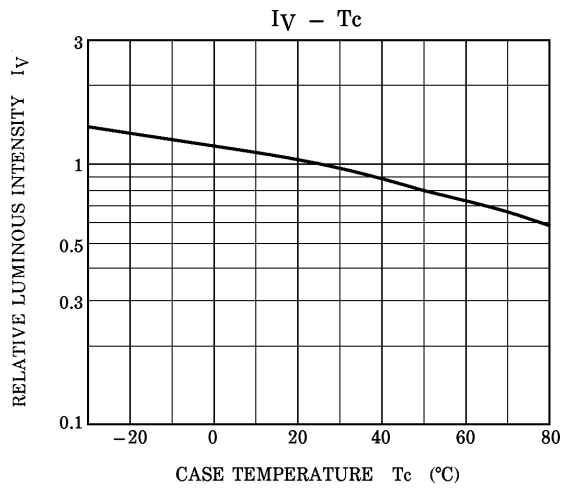
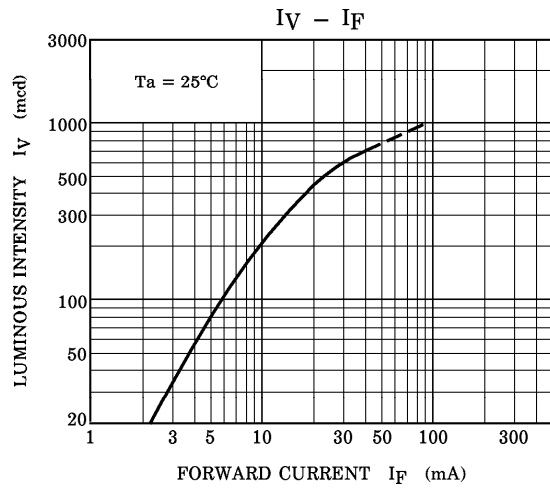
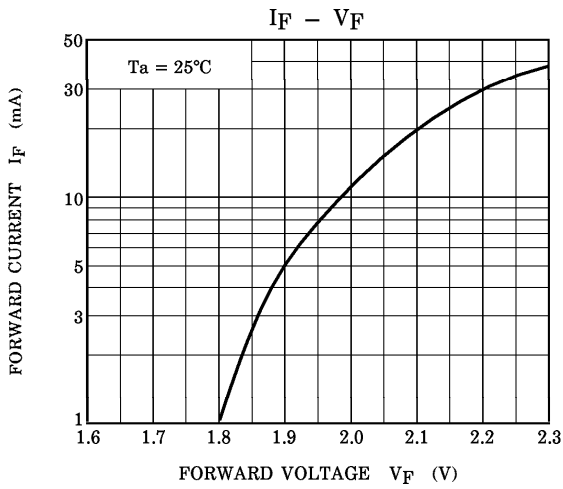
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**PRECAUTION**

Please be careful of the followings

- Soldering temperature : 260°C max      Soldering time : 3 s max  
(Soldering portion of lead : up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light. If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.



RADIATION PATTERN

$T_a = 25^\circ\text{C}$

